

Title (en)
IMAGE SENSOR

Title (de)
BILDSENSOR

Title (fr)
CAPTEUR D'IMAGES

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Application
EP 20736358 A 20200709

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Abstract (en)
[origin: WO2021008980A1] The present invention concerns a method for manufacturing an optoelectronic device comprising an optical sensor with organic photodiodes capable of capturing a radiation. The optical sensor covers an electronic circuit (101) with MOS transistors (102). The method comprises forming, on the optical sensor, on the side of the optical sensor opposite the electronic circuit, a first layer (201) that is transparent to said radiation, the first layer having a flat face on the side opposite the optical sensor; and forming a second layer (301) on said face, the second layer being oxygen-tight and watertight.

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